ADLINK
LEADING EDGE AI COMPUTING

Embedded MXM Modules
NVIDIA Ada Lovelace Architecture

Mobile PCI Express Modules with NVIDIA Embedded GPUs



• EGX-MXM-AD2000



• EGX-MXM-AD3500



• EGX-MXM-AD5000

Features

- NVIDIA embedded graphics based on Ada Lovelace architecture
- Standard MXM 3.1 Type A/B form factor
- PCIe Gen 4 up to x16 interface
- Up to 9728 CUDA® cores, 76 RT Cores, and 304 Tensor Cores
- Up to 42.6 TFLOPS peak FP32 performance
- Up to 16GB GDDR6 memory, 256-bit
- Up to 576GB/s memory bandwidth
- Support up to 4 DP 1.4a displays, 115W TGP
- 5-year availability

Ordering Information

EGX-MXM-AD2000	Embedded NVIDIA® RTX™ ADA 2000, MXM 3.1 Type A, 82 x 70mm, PCIe Gen4 x8
Extended Temperature	
• t2EGX-MXM-AD2000-35W	ETT -40˚C – 85˚C
• t2EGX-MXM-AD2000-35W-cc	ETT -40˚C – 85˚C, Conformal coated
EGX-MXM-AD3500	Embedded NVIDIA® RTX™ ADA 3500, MXM 3.1 Type B, 82 x 105mm, PCIe Gen4 x16
EGX-MXM-AD5000	Embedded NVIDIA® RTX™ ADA 5000, MXM 3.1 Type B, 82 x 105mm, PCIe Gen4 x16

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Specifications







Model Name	EGX-MXM-AD2000	EGX-MXM-AD3500	EGX-MXM-AD5000
Graphic Core			
Graphic Architecture	NVIDIA RTX™ 2000 ADA AD107-975 GPU	NVIDIA RTX™ 3500 ADA AD104-925 GPU	NVIDIA RTX™ 5000 ADA AD103-950-955 GPU
Memory	8GB GDDR6 memory, 128-bit, Bandwidth: 256GB/s	12GB GDDR6 memory, 192-bit, Bandwidth: 432GB/s	16GB GDDR6 memory, 256-bit, Bandwidth: 576GB/s
ECC Support	Yes	Yes	Yes
GPGPU Computing			
CUDA® Cores	3,072 CUDA® Cores, 14.5 TFLOPS Peak FP32 Performance	5,120 CUDA® Cores, 23 TFLOPS Peak FP32 Performance	9,728 CUDA® Cores, 42.6 TFLOPS Peak FP32 Performance
Tensor Cores	96	160	304
RT Cores	24	40	76
Compute API	CUDA® Toolkit 8.0 and above, CUDA® Compute version 8 and above, OpenCL™ 1.2		
Graphics API	DirectX® 12.1, OpenGL® 4.6		
Display			
Display Outputs	3x DP 1.4a	4x DP 1.4a	4x DP 1.4a
	HDMI 2.1, 4K at 120Hz or 8K at 60Hz with 10-bit color depth		
Interface	PCIe Gen4 x8	PCIe Gen4 x16	PCIe Gen4 x16
Mechanicals			
Dimensions	82 (W) x 70 (D) x 4.8 (H) mm	82 (W) x 105 (D) x 4.8 (H) mm	
Form Factor	Standard MXM 3.1 Type A	Standard MXM 3.1 Type B	
Environmental			
Operating Temperature	Standard: 0˚C – 55˚C Extended Temperature: -40˚C – 85˚C		
Storage Temperature	-40˚C – 85˚C		
Module Power Consumption	60W	115W	
SW Support			
OS Support	Windows 11, 10 & Linux Drivers, 64-bit		

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